

LISTING OF CLAIMS:

The present listing of claims replaces all prior listings or versions of claims in the present application.

1. (Currently Amended) A photosensitive resin composition comprising:

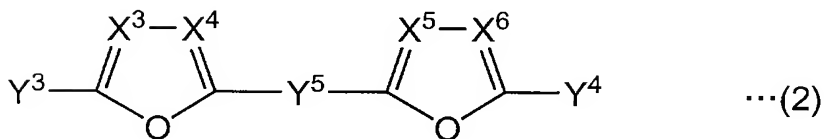
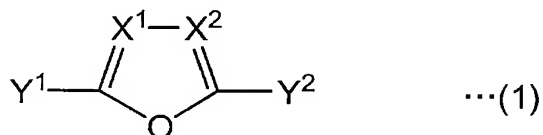
(A) a binder polymer;

(B) a photopolymerizing compound with an ethylenic unsaturated bond;

(C) a photopolymerization initiator; and

(D) a compound represented by the following general formula (1) or (2);

~~{Chemical Formula-1}~~



{wherein X¹, X², X³, X⁴, X⁵ and X⁶ each independently represent a CH group, a CCH₃ group, a CC₂H₅ group or nitrogen, Y¹, Y², Y³ and Y⁴ each independently represent optionally substituted aryl, and Y⁵ represents optionally substituted arylene}.

2. (Original) A photosensitive resin composition according to claim 1, wherein component (C) contains a 2,4,5-triarylimidazole dimer.

3. (Currently Amended) A photosensitive resin composition according to claim 1 or 2, wherein component (B) contains a bisphenol A-type (meth)acrylate compound.

4. (Currently Amended) A photosensitive resin composition according to ~~any one of~~ claims 1-~~to~~3, wherein the acid value of component (A) is 30-200 mgKOH/g and the weight-average molecular weight is 20,000-300,000.

5. (Currently Amended) A photosensitive resin composition according to ~~any one of~~ claims 1-~~to~~4, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

6. (Currently Amended) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to ~~any one of~~ claims 1-~~to~~5 formed on the support.

7. (Currently Amended) A resist pattern forming method comprising the steps ~~of which comprises~~

laminating a photosensitive resin composition layer for a photosensitive element according to claim 6 on a circuit forming board;

irradiating prescribed sections of the photosensitive resin composition layer with active light rays for photocuring of ~~the-exposed sections~~; and then

removing ~~the-non-exposed sections~~.

8. (Currently Amended) A process for manufacturing a printed circuit board comprising the steps of ~~which comprises~~ etching or plating a circuit forming board having a

resist pattern formed thereon by a resist pattern forming method according to claim 7.

9. (NEW) A photosensitive resin composition according to claim 2, wherein component (B) contains a bisphenol A-type (meth)acrylate compound.

10. (NEW) A photosensitive resin composition according to claim 9, wherein the acid value of component (A) is 30-200 mgKOH/g and the weight-average molecular weight is 20,000-300,000.

11. (NEW) A photosensitive resin composition according to claim 2, wherein the acid value of component (A) is 30-200 mgKOH/g and the weight-average molecular weight is 20,000-300,000.

12. (NEW) A photosensitive resin composition according to claim 3, wherein the acid value of component (A) is 30-200 mgKOH/g and the weight-average molecular weight is 20,000-300,000.

13. (NEW) A photosensitive resin composition according to claim 2, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

14. (NEW) A photosensitive resin composition according to claim 3, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by

weight, the component (C) content is 0.01-20 parts by weight and the component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

15. (NEW) A photosensitive resin composition according to claim 4, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

16. (NEW) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 2 formed on the support.

17. (NEW) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 3 formed on the support.

18. (NEW) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 4 formed on the support.

19. (NEW) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 5 formed on the support.